


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	MMS/16/9626	
<b>1.3 Title of PCN</b>	Additional capacity through High Density Matrix Leadframe in ST Muar (Malaysia) - STM32F100 128K and STM8L15x 64K products in LQFP 64 10x10 package	
<b>1.4 Product Category</b>	STM32F100 128K and STM8L15x 64K products in LQFP 64 10x10 package	
<b>1.5 Issue date</b>	2016-02-16	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	MATTE PIERRE
<b>2.1.2 Phone</b>	+1 7814028596
<b>2.1.3 Email</b>	pierre.matte@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Michel BUFFA
<b>2.1.2 Marketing Manager</b>	Daniel COLONNA
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer of a full process or process brick (process step, control plan, recipes) from one site to another site	Assembly site	ST Muar (Malaysia), STATS ChipPAC Shanghai (China), Amkor ATP (Philippines)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	The qualified assembly plants are ST Muar (Malaysia), STATS ChipPAC Shanghai (China) and Amkor ATP (Philippines). The Bill of Materials is described in PCN_9626_Additional information document.	To the current sources, we add an assembly line in ST Muar (Malaysia) with High Density Matrix leadframe. The Bill of Materials is described in PCN_9626_Additional information document.
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	no change	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	To increase assembly capacity on an existing line, already qualified, with High Density Matrix leadframe.
<b>5.2 Customer Benefit</b>	DOUBLE SOURCING

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	See information in PCN_9626_Additional information document.
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2016-04-15
<b>7.2 Intended start of delivery</b>	2016-05-15
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	PCN_9626 - MCDRER1411 Reliability plan addendum ST Muar LQFP 10x10.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2016-02-16

**9. Attachments (additional documentations)**

9626PpPrdtLst.pdf  
PCN\_9626\_Additional information.pdf  
PCN\_9626 - MCDRER1411 Reliability plan addendum ST Muar LQFP 10x10.pdf  
MMS MCDRER1411 v10 Qualification Report LQFP10x10 Muar.pdf

**10. Affected parts**

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F100RBT6B	

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